

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Konecni et al.

Serial No.: 08/988,686

Filed: 12/11/97

For: **METHOD AND SYSTEM FOR SELECTIVELY COUPLING A CONDUCTIVE MATERIAL TO A SURFACE OF A SEMICONDUCTOR DEVICE**



Docket No.: TI-22166

Art Unit: 2814

Examiner: Eaton, K.

21p/2814
#a/sub spec. N/E
10/5/99
C. McHenry

Assistant Commissioner for Patents
Washington, DC 20231

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(a)
I hereby certify that the above correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231 on

August 31, 1999

Jeff Quan

LETTER

Dear Sir:

With regard to the Office Action mailed May 28, 1999, and the Applicant's Response mailed August 30, 1999, and in connection with the above-identified application, Applicant respectfully submits the clean copy of the instant specification that was inadvertently omitted from the Response mailed yesterday. Please charge any necessary fees to the deposit account of Texas Instruments, Inc., Deposit Account No. 20-0668.

Respectfully submitted,

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